

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Genum Corporation	10/22/2007

RECEIVING PARTY DATA

Name:	Sound Design Technologies Ltd., a Canadian corporation
Street Address:	970 Fraser Drive
City:	Burlington, Ontario
State/Country:	CANADA
Postal Code:	L7L 5P5

PROPERTY NUMBERS Total: 24

Property Type	Number
Patent Number:	4901030
Patent Number:	5023543
Patent Number:	5029281
Patent Number:	5056151
Patent Number:	5220220
Patent Number:	5832097
Patent Number:	6633202
Patent Number:	6937738
Patent Number:	7076073
Patent Number:	7031482
Patent Number:	7113589
Patent Number:	7181034
Patent Number:	7242778
Patent Number:	7251339
Patent Number:	5920771

PATENT

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Patent Number:	5293071
Patent Number:	6631087
Patent Number:	5478517
Patent Number:	6583019
Patent Number:	5528457
Patent Number:	6218722
Patent Number:	6734570
Patent Number:	6133626
Patent Number:	6731541

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	SOU03 A-100
NAME OF SUBMITTER:	Donald S. Gardner

Total Attachments: 10

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ASSIGNMENT OF PATENTS

WHEREAS, THE UNDERSIGNED, GENNUM CORPORATION ("Assignor") is the owner of the inventions set forth in and the patents and patent applications set out in Schedule A attached hereto ("**Patents**");

WHEREAS, SOUND DESIGN TECHNOLOGIES LTD. ("Assignee"), whose full post office address and whose principal office or place of business is 970 Fraser Drive, Burlington, Ontario, Canada, L7R 3Y3, wishes to acquire all of the Assignor's right, title and interest in and to the Patents, and the Assignor wishes to transfer all such right, title and interest to the Assignee;

NOW THEREFORE Assignor, in consideration of the sum of ten dollars (\$10.00) the receipt of which is hereby acknowledged, and other consideration paid pursuant to the Asset Purchase Agreement dated the date hereof and to which the Assignor and Assignee are parties, confirms that it has assigned and for greater certainty hereby assigns unto Assignee all of the Assignor's right, title, and interest in and to the Patents, including the full and exclusive right, title and interest in and to the said inventions in the United States and in all foreign countries and the entire right, title and interest in and to any and all Letters Patent which may be granted therefore in the United States and in any and all foreign countries and in and to any and all divisions, reissues, continuations, continuations-in-part, registrations, additions, and/or extensions thereof or thereto, including the full right to claim for any such applications the benefits of the International Convention, together with all rights of action resulting from any prior unauthorized use, including any infringement of the Patents, and the right to claim damages and such other relief as is appropriate, and the benefits and obligations of licenses to third parties, including all rights to royalty and other income connected with such inventions and Patents, the same to be held and enjoyed by the Assignee, its successors, and assigns as fully and effectually as they would have been held and enjoyed by the Assignor had this assignment and sale not been made.

ASSIGNOR hereby authorizes and requests the Patent Office officials in the United States and in any and all foreign countries to issue any and all of said Letters Patent, when granted, to said Assignee as the owner of the entire right, title and interest in and to the same, for the sole use and behoof of said Assignee, its successors and assigns.

FURTHER, Assignor agrees to sign all lawful papers, execute all divisional, continuation, continuation-in-part, substitution, renewal, extension, addition and reissue applications, execute all necessary assignment papers, as may be reasonably requested by Assignee and at Assignee's expense, to cause any and all of said Letters Patent to be issued to said Assignee. Assignor agrees to, at Assignee's expense, provide reasonable assistance and evidence as may be requested by Assignee to aid Assignee, its successors and assigns, to obtain and enforce proper protection for said inventions and Patents in the United States and in any and all foreign countries.

AND the Assignor hereby undertakes to, without further consideration but at the expense of the Assignee, execute all such documents and do all such acts as may be reasonably necessary to perfect such assignment.

EXECUTED at the City of Burlington, Ontario, Canada this 22 day of Oct, 2007.

GENNUM CORPORATION

Per: 

Name: FRANZ J. FINK

Title: PRESIDENT + CEO

Before me personally appeared said FRANZ J. FINK and acknowledged the foregoing instrument to be his free act and deed this 22 day of Oct, 2007.


Notary Public CC Fink

SOUND DESIGN TECHNOLOGIES LTD.

Per: _____

Name: Catherine Babon Scanlon

Title: CFO

Before me personally appeared said _____ and acknowledged the foregoing instrument to be his free act and deed this _____ day of _____, 2007.

AND the Assignor hereby undertakes to, without further consideration but at the expense of the Assignee, execute all such documents and do all such acts as may be reasonably necessary to perfect such assignment.

EXECUTED at the City of Burlington, Ontario, Canada this _____ day of _____, 2007.


GENNUM CORPORATION

Per: _____
Name: _____
Title: _____

Before me personally appeared said _____ and acknowledged the foregoing instrument to be his free act and deed this _____ day of _____, 2007.

Notary Public

SOUND DESIGN TECHNOLOGIES LTD.

Per:  _____
Name: Catherine Babon Scanlon
Title: CFO

Before me personally appeared said Catherine Babon Scanlon and acknowledged the foregoing instrument to be his free act and deed this 30th day of October, 2007.

 _____
Notary Public

My Commission Expires
August 15, 2007

SCHEDULE "A"

Patents

Advanced Substrate

Patent Application – Advanced Substrate

Country	Patent Application	Application No.	Publication Date
US	Microphone Carrier Chip with Acoustic Cavity (excludes IP relating to the electrical and mechanical design of the custom carrier substrate)	11/862,471	Not Published (Filed September 27, 2007)

Hearing Instruments

Patents

Country	Patent	Patent No.	Date of Patent
US	Operational Amplifier Stages	US 4,901,030	February 13, 1990
US	Temperature Compensated Voltage Regulator and Reference Circuit	US 5,023,543	June 11, 1991
US	Clipping Circuit	US 5,029,281	July 2, 1991
US	Electrical Component Connection and Combinations of Electrical Components	US 5,056,151	October 8, 1991
US	Noise Suppression System	US 5,220,220	June 15, 1993
US	Multi-Channel Synchronous Companding System	US 5,832,097	November 3, 1998
US	Precision Low Jitter Oscillation Circuit	US 6,633,202	October 14, 2003
US	Digital Hearing Aid System	US 6,937,738	August 30, 2005
US	Digital Quasi RMS Detector	US 7,076,073	July 11, 2006
US	Precision Low Jitter Oscillation Circuit	US 7,031,482	April 18, 2006
US	Low Power Reconfigurable Hearing Instrument	US 7,113,589	September 26, 2006
US	Inter-Channel Communication in a Multi-Channel Digital Hearing Instrument	US 7,181,034	February 20, 2007
US	Hearing Instrument with Self-Diagnostics	US 7,242,778	July 10, 2007
US	Wireless Remote Control for a Hearing Instrument	US 7,251,339	July 31, 2007
UK (from EP	Precision Low Jitter Oscillation	1267491	January 11, 2006

application)	Circuit	(EP 02008038.8)	
France (from EP appl.)	Precision Low Jitter Oscillation Circuit	1267491 (EP 02008038.8)	January 11, 2006
Germany (from EP appl.)	Precision Low Jitter Oscillation Circuit	1267491 (EP 02008038.8)	January 11, 2006
Italy (from EP appl.)	Precision Low Jitter Oscillation Circuit	1267491 (EP 02008038.8)	January 11, 2006
Spain (from EP appl.)	Precision Low Jitter Oscillation Circuit	1267491 (EP 02008038.8)	January 11, 2006
Switzerland (from EP appl.)	Precision Low Jitter Oscillation Circuit	1267491 (EP 02008038.8)	January 11, 2006
Denmark (from EP appl.)	Precision Low Jitter Oscillation Circuit	1267491 (EP 02008038.8)	January 11, 2006
Canada	Digital Hearing Aid System	2381516	July 3, 2007
Canada	Digital Quasi RMS Detector	2382358	January 9, 2007
UK (from EP appl.)	Inter-Channel Communication in a Multi-Channel Digital Hearing Instrument	1251715 (EP 02008747.4)	January 4, 2006
Denmark (from EP appl.)	Inter-Channel Communication in a Multi-Channel Digital Hearing Instrument	1251715 (EP 02008747.4)	January 4, 2006
Spain (from EP appl.)	Inter-Channel Communication in a Multi-Channel Digital Hearing Instrument	1251715 (EP 02008747.4)	January 4, 2006
Germany (from EP appl.)	Inter-Channel Communication in a Multi-Channel Digital Hearing Instrument	1251715 (EP 02008747.4)	January 4, 2006
Switzerland (from EP appl.)	Inter-Channel Communication in a Multi-Channel Digital Hearing Instrument	1251715 (EP 02008747.4)	January 4, 2006
Italy (from EP appl.)	Inter-Channel Communication in a Multi-Channel Digital Hearing Instrument	1251715 (EP 02008747.4)	January 4, 2006
France (from EP appl.)	Inter-Channel Communication in a Multi-Channel Digital Hearing Instrument	1251715 (EP 02008747.4)	January 4, 2006
Canada	Low-Noise Directional Microphone System	2420989	December 15, 2006
Australia	Temperature Compensated Voltage Regulator and Reference Circuit	624052	September 22, 1992
Australia	Electrical Component Connection and Combinations of Electrical Components	653707	February 10, 1995
Canada	Operational Amplifier Stages	1312359	January 5, 1993

Patent Applications

Country	Patent Application	Patent Application No./Publication No.	Publication Date
US	Low-Noise Directional Microphone System	10/383,141 US 2003/0169891	September 11, 2003
US	Digital Hearing Aid System	11/150,896 US 2005/0232452	October 20, 2005
US	System and Method for Detecting the Insertion or Removal of a Hearing Instrument from the Ear Canal	10/812,826 US 2004/0196992	October 7, 2004
US	Hearing Aid Vent with Acoustical Feedback	10/818,258 US 2004/0218772	November 4, 2004
US	System and Method for Transmitting Audio via a Serial Data Port in a Hearing Instrument	10/822,519 US 2004/0202340	October 14, 2004
US	System and Method for Diagnosing Manufacturing Defects in a Hearing Instrument	11/302,794 US 2006/0139030	June 29, 2006
US	Faceplate Moat and Cutout for Hearing Instrument	11/003,667 US 2006/0120547	June 8, 2006
US	In-Ear Monitoring System and Method	11/158,636 2005/0281423	December 22, 2005
US	System and Method of Detecting Brain Waves	11/264,215 US 2006/0094974	May 4, 2006
US	In-Ear Monitoring System and Method with Bidirectional Channel	11/158,620 US 2005/0281422	December 22, 2005
US	Hearing Instrument with Acoustic Blocker, In-The-Ear Microphone and Speaker	11/605,917	Not Published (Filed November 29, 2006)
US	Low Power Audio Processing Circuitry for a Musical Instrument	11/590,016 US 2007/0095195	May 3, 2007
US	Audio Processing System and Method	11/481,171	Not Published (Filed July 5, 2006)
US	Low Power Reconfigurable Hearing Instrument Device	11/523,147 US 2007/0121977	May 31, 2007
US	Wax Guard for a Hearing Instrument	11/766,994	Not Published (Filed June 22, 2007)
US	Interchannel Communication in a Multi-Channel Digital Hearing Instrument	11/656,678 US 2007/0127752	June 7, 2007
US	First Person Acoustic Environment System and Method	11/158,493 US 2005/0281421	December 22, 2005
Canada	Precision Low Jitter Oscillation Circuit	2381105	(Filed April 9, 2002)
EP	Digital Hearing Aid System	02008393.7	October 23, 2002
Canada	Digital Hearing Aid System	2582648	(filed April 11, 2002)
EP	Digital Quasi RMS Detector	02008767.2	October 23, 2002
Canada	Low Power Reconfigurable	2398333	(filed August 15, 2002)

Country	Patent Application	Patent Application No./Publication No.	Publication Date
	Hearing Instrument		
EP	Low Power Reconfigurable Hearing Instrument	02018397.6	February 19, 2003
Canada	Inter-Channel Communication in a Multi-Channel Digital Hearing Instrument	2382362	(filed April 18, 2002)
Canada	Hearing Instrument with Self-Diagnostics	2463195	(filed July 10, 2007)
EP	Hearing Instrument with Self-Diagnostics	04008506.0	October 13, 2004
Canada	Wireless Remote Control for a Hearing Instrument	2462750	(filed April 1, 2004)
EP	Wireless Remote Control for a Hearing Instrument	04007976.6	October 6, 2004
EP	Low-Noise Directional Microphone System	2420989	December 15, 2006
Canada	System and Method for Detecting the Insertion or Removal of a Hearing Instrument from the Ear Canal	2462634	(filed March 31, 2004)
EP	System and Method for Detecting the Insertion or Removal of a Hearing Instrument from the Ear Canal	04007975.8	October 6, 2004
Canada	Hearing Aid Vent with Acoustical Feedback	2463206	(filed April 5, 2004)
EP	Hearing Aid Vent with Acoustical Feedback	04008221.6	October 6, 2004
Canada	System and Method for Transmitting Audio via a Serial Data Port in a Hearing Instrument	2464025	(filed April 13, 2004)
EP	System and Method for Transmitting Audio via a Serial Data Port in a Hearing Instrument	04008778.5	October 13, 2004
PCT	System and Method for Diagnosing Manufacturing Defects in a Hearing Instrument	WO 2006/063455	June 22, 2006
Japan	System and Method for Diagnosing Manufacturing Defects in a Hearing Instrument	Not issued yet (WO 2006/063455)	(filed June 13, 2007)
EP	System and Method for Diagnosing Manufacturing Defects in a Hearing Instrument	05821099.7	September 26, 2007
EP	In-Ear Monitoring System and Method	05759513.4	April 18, 2007
EP	In-Ear Monitoring System and Method with Bidirectional Channel	05761946.2	April 18, 2007
EP	First Person Acoustic Environment	05761961.1	April 18, 2007

Country	Patent Application	Patent Application No./Publication No.	Publication Date
	System and Method		
Japan	Audio Processing System and Method	2007-170551	(filed June 28, 2007)
EP	Audio Processing System and Method	07012947.3	(filed July 2, 2007)
PCT	Hearing Instrument with Acoustic Blocker, In-The-Ear Microphone and Speaker	Not yet available	Not Published (Filed October 19, 2007)
PCT	Wax Guard for a Hearing Instrument	Not yet available	Not Published (Filed October 19, 2007)
Japan	Multi-Channel Synchronous Companding System	9-1997-512255	Filed Sept. 4, 1996
Canada	Multi-Channel Synchronous Companding System	2232625	Filed Sept. 4, 1996

Manufacturing

Patents – Manufacturing

Country	Patent	Patent No.	Date of Patent
US	Antifuse Based on Silicided Polysilicon Bipolar Transistor	US 5,920,771	July 6, 1999
US	Bump Structure for Bonding to a Semiconductor Device	US 5,293,071	March 8, 1994
US	Low Voltage Single Poly Deep Sub-Micron Flash Eeprom	US 6,631,087	October 7, 2003
US	Method for Molding IC Chips	US 5,478,517	December 26, 1995
US	Perimeter Anchored Thick Film Pad	US 6,583,019	June 24, 2003
US	Method and Structure for Balancing Encapsulation Stresses in a Hybrid Circuit Assembly	US 5,528,457	June 18, 1996
US	Antifuse Based on Silicided Polysilicon	US 6,218,722	April 17, 2001
US	Solder Bumped Substrate for a Fine Pitch Flip-Chip Integrated Circuit Package	US 6,734,570	May 11, 2004
US	Three dimensional packaging configuration for multi-chip module assembly	US 6,133,626	October 17, 2000
US	Low Voltage Single Poly Deep Sub-Micron Flash Eeprom	US 6,731,541	May 4, 2004
Canada	Antifuse Based on Silicided Polysilicon Bipolar Transistor	2197627	January 3, 2006
UK	Antifuse Based on Silicided Polysilicon Bipolar Transistor	1129520	July 16, 2003
Canada	Three dimensional packaging configuration for multi-chip module assembly	2218307	January 3, 2006
Singapore	Three dimensional packaging configuration for multi-chip module assembly	72244	May 7, 2002
EP	Three dimensional packaging configuration for multi-chip module assembly	1025589	January 25, 2006
UK	Method for Molding IC Chips	0746455	August 12, 1998

Patent Application – Manufacturing

Country	Patent Application	Patent Application No.	Publication Date
Canada	Perimeter Anchored Thick Film Pad	2412030	May 19, 2003

EP	Perimeter Anchored Thick Film Pad	02025833.1	March 8, 2006
Japan	Antifuse Based on Silicided Polysilicon Bipolar Transistor	10-535191	(Filed February 13, 1998)